

HEAT SINK COMPOUND

Anabond -652 is a thermally conductive but electrically insulating system. It will not harden or dry out or melt even after 1000 hours @ 200°C with good dielectric properties.

SALIENT FEATURES :

- High thermal conductivity (0.437 w/mk)
- Non curing compound
- Dissipates heat from the device
- Increase the over all efficiency of the device.
- High dielectric strength (7.2 kv/mm)

APPLICATIONS :

Mounting studs of transistors, diodes & silicon rectifiers to provide effective heat seal.

